

SONY

Sony Semiconductor
Products Lead-free Package

*Semiconductor Products
Lead-free Package*





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1. The Need for Lead-free Products

1-1. Background

Scientists have reported various adverse environmental effects attributable to the use of lead. When accumulated in the human body through drinking water or food, it can retard growth in children and cause mental disorders in adults. The solder used in electronic assemblies contains substantial amounts of lead about 37 percent. If printed circuit boards disposed of in landfills, etc. are exposed to acid rain, the lead will leach out of the solder. The lead may then contaminate groundwater and rivers, and hence it is absorbed into the human body through drinking water.

The development of Lead-free solders and mount technology and the recovery and recycling of electronic products have become of paramount importance for protecting the global environment.

1-2. Trends in the Regulation of Lead Use

Europe: In 2000, the OECD tightened the standard for lead content in groundwater from 0.05mg/l to 0.025mg/l. The final draft of the EU directive on waste electrical and electronic equipment (WEEE) calls for the substitution of lead, cadmium, hexavalent chromium and halogenated flame retardants by January 1, 2008, except in special applications.

United States: A bill providing for the regulation of lead used in electric appliances was submitted to Congress in 1990 (with electronic products being excluded). The use of lead in gasoline, food cans, pipes, home paints and other products has either been prohibited or restricted, and there is growing pressure for the total elimination of lead.

Japan: The Law Concerning Waste Disposal and Sanitation (1991) requires that industrial waste in which 0.3mg/l or more of lead has been detected in elution tests be treated in controlled disposal plants. The Water Contamination Prevention Law (1994) strengthened the standard for lead content in rivers, etc. from 0.1mg/l to 0.01mg/l. In addition, the Electrical Appliance Recycling Law, which will be fully enforced, is considered to obligate producers to take the responsibility for recovering or making harmless toxic substances containing lead.



2. Sony's Strategy

2-1. Corporate Policy

Sony aims to introduce Lead-free solder for all models produced in Japan and overseas by March 2001 and March 2002, respectively.

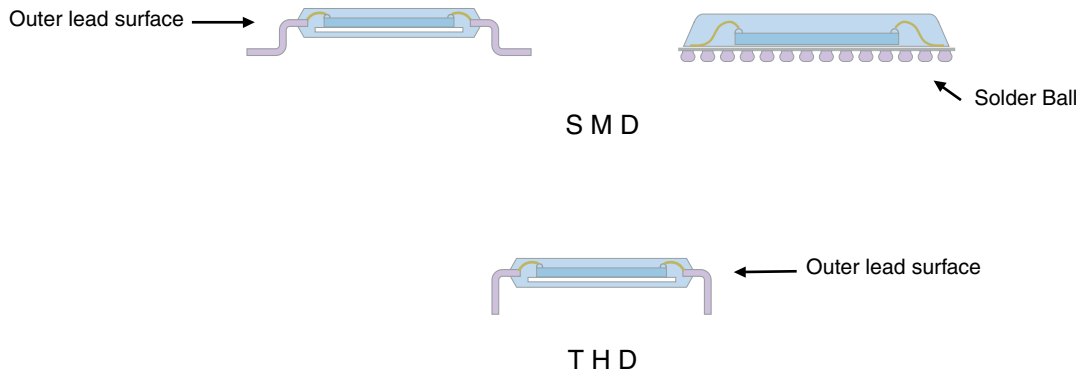
2-2. Semiconductor Group's Approach

Sony has already launched a number of semiconductor products with Lead-free external terminals. It plans to introduce Lead-free products progressively in all semiconductor categories, starting in the fall of 2000.



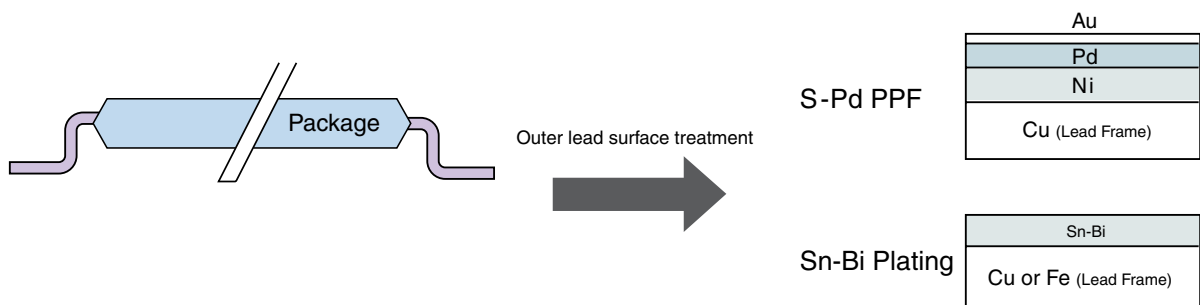
3. Developing Lead-free Semiconductors

3-1. Electrode Section of Lead-free



3-2. Lead-free Specifications

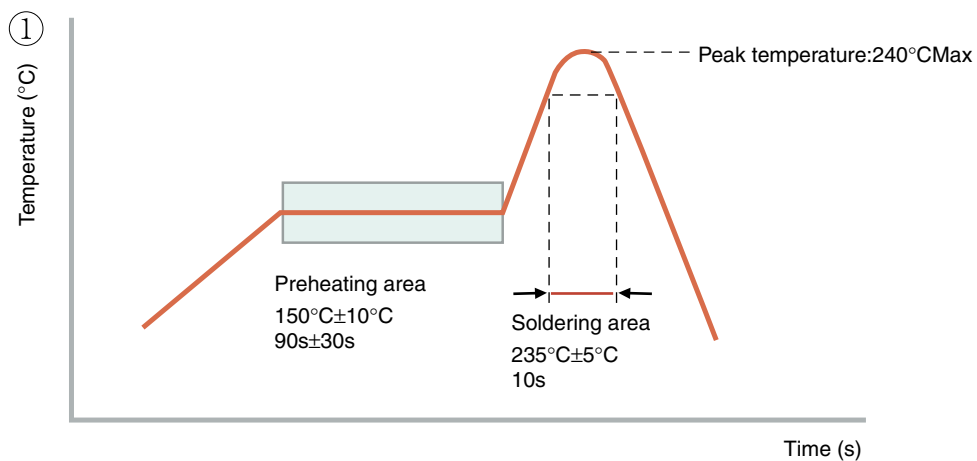
Type	Present	Lead-free
S M D	Sn-Pb Plating S-Pd PPF Ni / Au Plating Sn-Pb Ball	S-Pd PPF or Sn-Bi Plating Same as Present Same as Present Under Development
T H D	Sn-Pb Plating S-Pd PPF Ni / Au Plating Sn Plating	S-Pd PPF or Sn-Bi Plating Same as Present Same as Present Same as Present



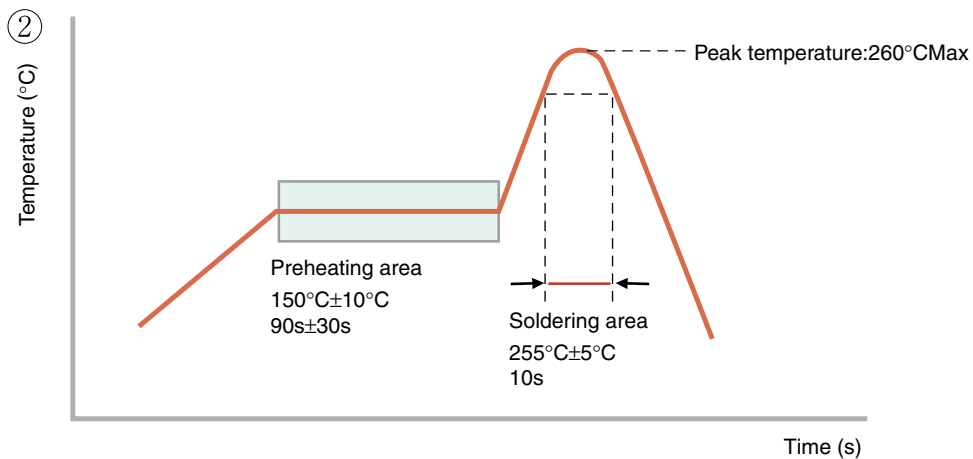
4. Heat-resistance of Solder

- For Lead-free solder, the maximum temperature during mounting processes will be 260°C for both re-flow and flow soldering processes.
- Solder heat-resistance varies with different products. Contact your local sales representative for details.

Standard Temperature Profile for Lead Solder (Sn-Pb eutectic)



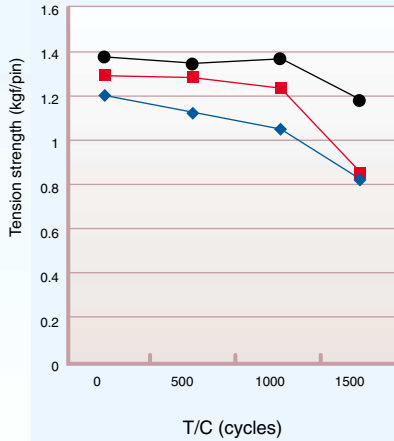
Standard Temperature Profile for Lead-free Solder



5. Results of Soldering Tests

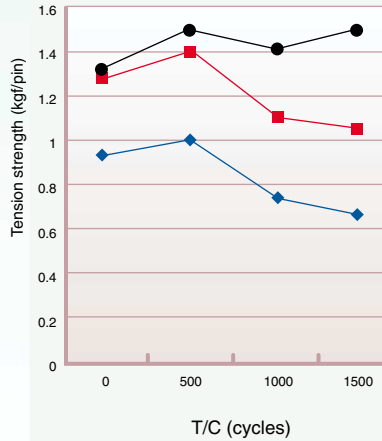
Mount Reliability (Tension Strength of Terminals)

Composition of Solder Paste
Sn-37Pb



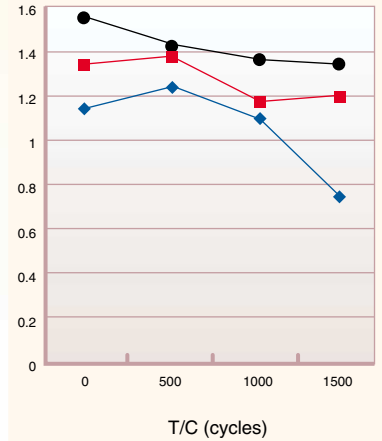
Sample: QFP-208pin (Cu Alloy)
Mount type: Based on present profile
T/C item: Based on SS-00250

Composition of Solder Paste
Sn-2.5Ag-1Bi-0.5Cu



Sample: QFP-208pin (Cu Alloy)
Mount type: Based on SS-00250 designated profile
T/C item: Based on SS-00250

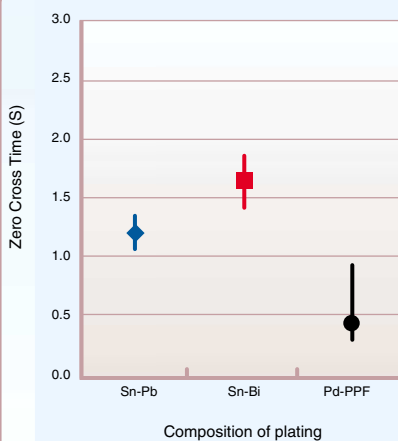
Composition of Solder Paste
Sn-3.5Ag-0.75Cu



Sample: QFP-208pin (Cu Alloy)
Mount type: Based on SS-00250 designated profile
T/C item: Based on SS-00250

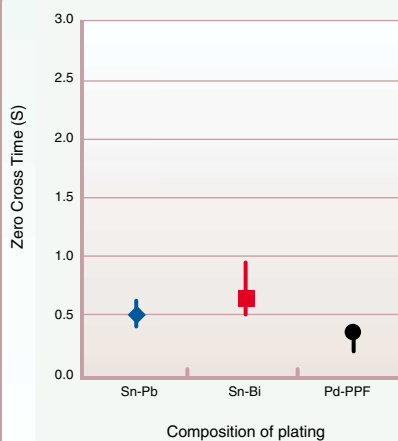
Solder Wettability

Composition of Soldering Bath
Sn-37Pb



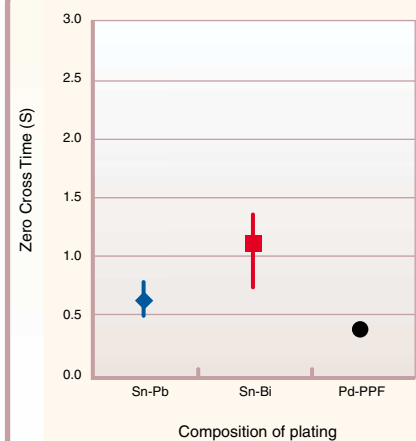
Measuring method ...
Quick heating programmed temperature method
Pretreatment ...
PCT(105°C 100%RH 1.22×10⁶PA(1.2atm)4h)
Flux ... Non-active type
Soldering bath temperature ... 230°C
Immersion rate ... 2mm/ s
Immersion depth ... 2mm
Duration ... 3 s
Sample size ... n=10leads

Composition of Soldering Bath
Sn-2.5Ag-1Bi-0.5Cu



Measuring method ...
Quick heating programmed temperature method
Pretreatment ...
PCT(105°C 100%RH 1.22×10⁶PA(1.2atm)4h)
Flux ... Non-active type
Soldering bath temperature ... 245°C
Immersion rate ... 2mm/ s
Immersion depth ... 2mm
Duration ... 3 s
Sample size ... n=10leads

Composition of Soldering Bath
Sn-3.5Ag-0.75Cu

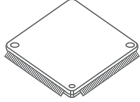


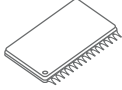


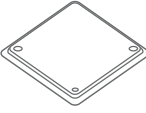

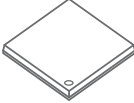

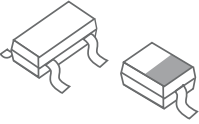

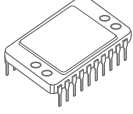


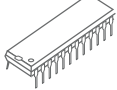


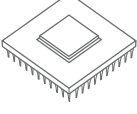

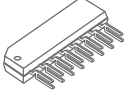

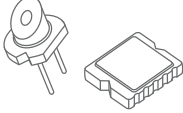



Measuring method ...
Quick heating programmed temperature method
Pretreatment ...
PCT(105°C 100%RH 1.22×10⁶PA(1.2atm)4h)
Flux ... Non-active type
Soldering bath temperature ... 245°C
Immersion rate ... 2mm/ s
Immersion depth ... 2mm
Duration ... 3 s
Sample size ... n=10leads

※ ●:Pd-PPF (Ni/Pd/Au) ■:Sn-Bi (Bi 3%) ◆:Sn-Pb (Pb 10)



6. Specifications for Lead-free Package Electrodes

Type	Category	Package		Lead-free specification				
		Name (Nominal)	Shape (Representative)	Pd plating	Sn-Bi plating	Au plating	Sn plating	Lead-free ball
SMD	Integrated circuit	QFP TQFP / LQFP QFN						
		SOP series						
		BGA						
		LGA						
	Discrete type	Mini mold package SSVC / SMVC						
THD	CCD	DIP / SOPseries						
	Integrated circuit	DIP series						
		PGA						
		SIP / ZIP SZIP						
	Laser Diode	CAN / Laser Coupler						

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